

Application No. 10/825,313  
Amendment dated March 6, 2006  
Reply to Office Action of December 6, 2005

Docket No.: 3722-0190PUS1

**AMENDMENTS TO THE SPECIFICATION**

Please add the following paragraph after the paragraph ending on page 7, line 8:

--Further scope of the applicability of the present invention will become apparent from the detailed description given hereinafter. However, it should be understood that the detailed description and specific examples, while indicating preferred embodiments of the invention, are given by way of illustration only, since various changes and modifications within the spirit and scope of the invention will become apparent to those skilled in the art from this detailed description.--

Please add the following paragraph before the paragraph beginning on page 7, line 10:

--The present invention will become more fully understood from the detailed description given hereinbelow and the accompanying drawings which are given by way of illustration only, and thus are not limitative of the present invention, and wherein:--

Please replace the paragraph beginning at page 10, line 2, with the following rewritten paragraph:

--The protection layer 26 is entirely immovable relative to the substrate structure 29 and includes, from bottom to top, first to third layers 26A to 26C. The first layer 26A provides a first stress against the substrate structure 29. The second layer 26B provides a second stress against the substrate structure 29. The third layer 26C provides a third stress against the substrate structure 29. --

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Please replace the paragraph beginning at page 15, line 13, with the following rewritten paragraph:

--The plate electrodes 22 and the metal mesh 23 may be made of the same material. For example, the plate electrodes 22 and the metal mesh 23 is the topmost metal film including the laminated aluminum layer 30 or laminated copper layer, formed in the IC manufacturing processes. A sense capacitance between the finger and each sense electrode is formed between each plate electrode 22 and the finger 1, and the metal mesh 23 is used for avoiding ESD damage. That is, each of the sense electrodes forms a sense result with the finger 1, and the sense result is sensed by the chip-type sensor. --